

Customer No.: 31561  
Application No.: 10/709,954  
Docket NO.: 11530-US-PA

### REMARKS

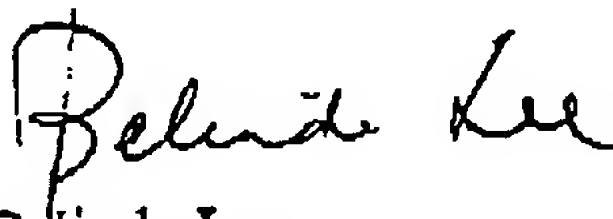
In response to the Office Action, mailed on June 30, 2005, a complete listing of all of the claims is presented herewith. Applicant would like to elect Group I, claims 1-11, drawn to an electrical package, classified in class 257, subclass 778. Please cancel the following two groups without waiver, prejudice or disclaimer:

1. Group II, claims 12-21, drawn to method of manufacturing an electrical package, classified in class 438, subclass 15+;
2. Group III, claims 22-30, drawn to an electrical package substrate, classified in class 361, subclass 1+.

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date: *July 27, 2005*

  
Belinda Lee  
Registration No.: 46,863

Jiang Chyun Intellectual Property Office  
7<sup>th</sup> Floor-1, No. 100  
Roosevelt Road, Section 2  
Taipei, 100  
Taiwan  
Tel: 011-886-2-2369-2800  
Fax: 011-886-2-2369-7233  
Email: [belinda@jciigroup.com.tw](mailto:belinda@jciigroup.com.tw)  
[Usa@jciigroup.com.tw](mailto:Usa@jciigroup.com.tw)